IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1. (Currently Amended) A vertical semiconductor device structure, comprising:
 - a substrate defining a substantially horizontal plane;
 - a source region;
 - a drain region;
- a gate electrode projecting vertically from disposed on said substrate and being electrically insulated therefrom, said gate electrode positioned vertically between said source region and said drain region;
- at least one semiconducting nanotube <u>including a first end electrically coupled with said</u> source region, a second end electrically coupled with said drain region, and a length extending vertically through said gate electrode between opposite <u>said</u> first and second ends <u>and being</u> electrically insulated from said gate electrode, said gate electrode gating said length when a voltage is applied to said gate electrode to define a channel region for current flow from said source to said drain;
- a gate dielectric electrically insulating said at least one semiconducting nanotube from said gate electrode;
- a source electrically coupled with said first end of said at least one semiconducting nanotube; and
- a drain electrically coupled with said second end of said at least one semiconducting nanotube.

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2. (Original) The semiconductor device structure of claim 1 wherein said source is composed of

a catalyst material effective for growing said at least one semiconducting nanotube.

(Currently Amended) The semiconducting semiconductor device structure of claim 1 wherein

said drain is composed of a catalyst material effective for growing said at least one

semiconducting nanotube.

4. (Original) The semiconductor device structure of claim 1 further comprising:

an insulating layer disposed between said drain and said gate electrode for electrically

isolating said drain from said gate electrode.

5. (Original) The semiconductor device structure of claim 1 further comprising:

an insulating layer disposed between said source and said gate electrode for electrically

isolating said source from said gate electrode.

6. (Currently Amended) The semiconducting semiconductor device structure of claim 1 wherein

said at least one semiconducting nanotube is composed of arranged carbon atoms.

7. (Cancelled)

8. (Currently Amended) The semiconducting semiconductor device structure of claim 1 wherein

said at least one semiconducting nanotube is oriented substantially perpendicular to said

horizontal plane.

9. (Currently Amended) The semiconducting semiconductor device structure of claim 1 further

comprising:

a plurality of semiconducting nanotubes extending vertically through said gate electrode.

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10. (Currently Amended) The semiconducting semiconductor device structure of claim 1 wherein said gate dielectric is disposed on said at least one semiconducting nanotube.

11-24. (Cancelled)

- 25. (Currently Amended) A semiconductor device structure, comprising:
 - a substrate defining a substantially horizontal plane;
 - [[a]] an electrically-conductive first plate disposed on said substrate,
- at least one nanotube projecting vertically from said first plate and electrically coupled with said first plate;
- [[a]] an electrically-conductive second plate positioned disposed vertically above said first plate;
- at least one nanotube having an end electrically coupled with said first plate and a length that extends from said end vertically into said second plate; and
- a dielectric layer electrically isolating disposed between said second plate [[from]] and said first plate, [[and]] said dielectric layer coating said length of said at least one carbon nanotube such that said at least one nanotube is electrically isolated from said second plate.
- 26. (Original) The semiconductor device structure of claim 25 wherein said at least one nanotube has a conducting molecular structure.
- 27. (Original) The semiconductor device structure of claim 25 wherein said at least one nanotube has a semiconducting molecular structure.
- 28. (Currently Amended) The semiconducting semiconductor device structure of claim 25 wherein said dielectric layer defines a coating that encases said at least one nanotube.

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29-32. (Cancelled)

33. (New) The semiconductor device structure of claim 1 wherein said gate electrode has a thickness approximately equal to the length of said at least one semiconducting nanotube.

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